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Bib Data Sheet

CONFIRMATION NO. 9497

<b>SERIAL NUMBER</b> 10/034,030	<b>FILING DATE</b> 12/19/2001 <b>RULE</b>	<b>CLASS</b> <del>438</del> 29	<b>GROUP ART UNIT</b> <del>2812</del> 3729	<b>ATTORNEY DOCKET NO.</b> JCLA8482
<b>APPLICANTS</b> Gwo-Ji Horng, Taoyuan Hsien, TAIWAN; Jen-I Kuo, Chiayii, TAIWAN; Feng-Ger Hsiau, Nantou Hsien, TAIWAN;  <b>** CONTINUING DATA *****</b> <i>None (inf)</i> <b>** FOREIGN APPLICATIONS *****</b> <i>None (inf)</i>				
<b>IF REQUIRED, FOREIGN FILING LICENSE GRANTED</b> <b>** 02/01/2002</b>				
Foreign Priority claimed <input type="checkbox"/> yes <input checked="" type="checkbox"/> no 35 USC 119 (a-d) conditions met <input type="checkbox"/> yes <input checked="" type="checkbox"/> no <input type="checkbox"/> Met after Allowance Verified and Acknowledged <i>[Signature]</i> Examiner's Signature Initials		<b>STATE OR COUNTRY</b> TAIWAN	<b>SHEETS DRAWING</b> 4	<b>TOTAL CLAIMS</b> 49
<b>INDEPENDENT CLAIMS</b> 7				
<b>ADDRESS</b> J.C. Patents, Inc. 4 Venture, Suite 250 Irvine, CA 92618				
<b>TITLE</b> Method of fabricating a ceramic substrate with a thermal conductive plug of a multi-chip package				
<b>FILING FEE RECEIVED</b> 1598	FEES: Authority has been given in Paper No. _____ to charge/credit DEPOSIT ACCOUNT No. _____ for following:		<input type="checkbox"/> All Fees	
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